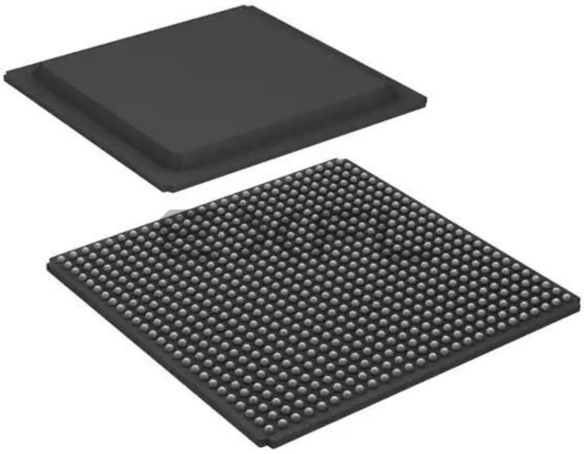

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	2320
Number of Logic Elements/Cells	20880
Total RAM Bits	1622016
Number of I/O	404
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	676-BGA
Supplier Device Package	676-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp20-5fg676c

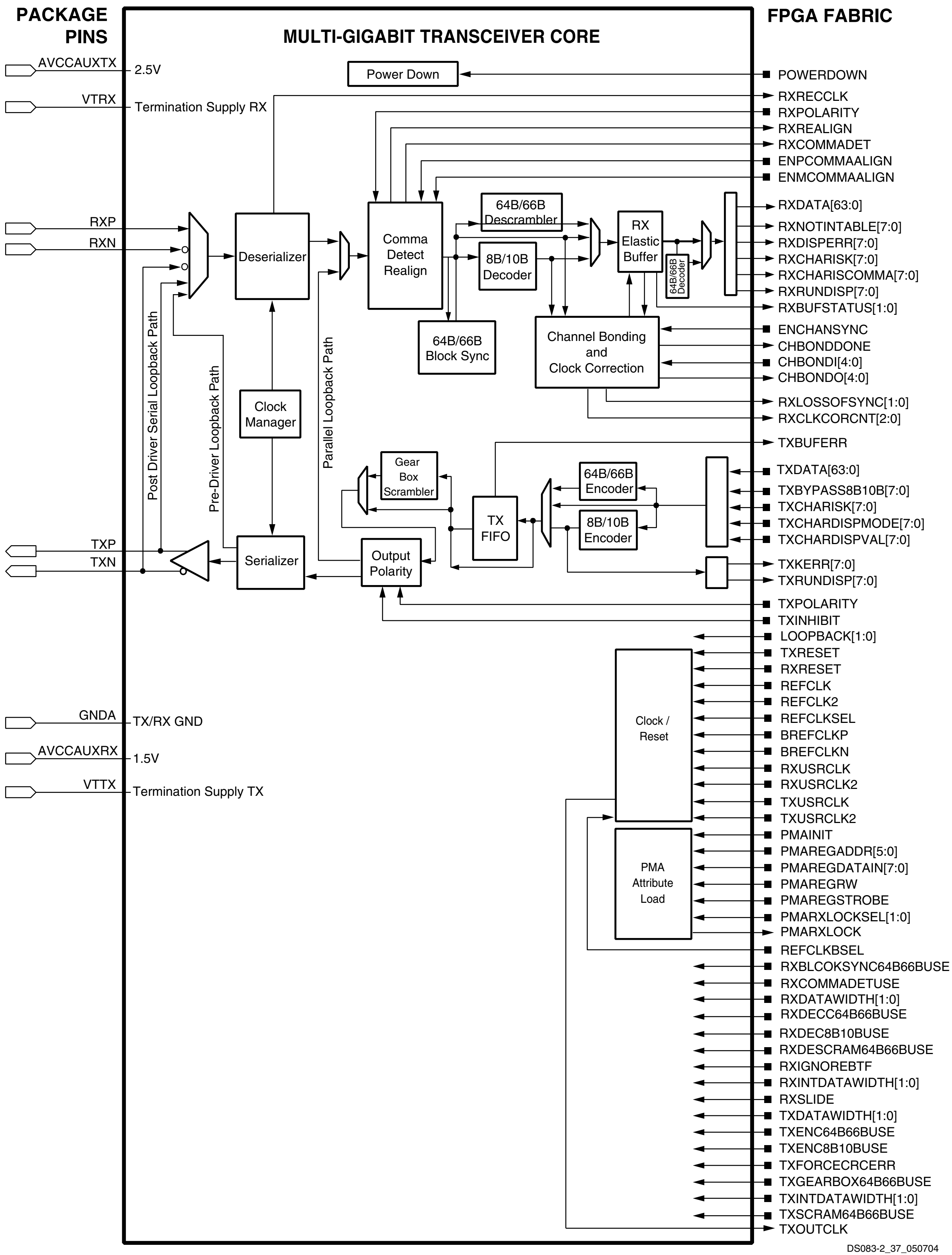

Figure 4: **RocketIO X Transceiver Block Diagram**

Serializer

The serializer multiplies the reference frequency provided on REFCLK by 20. The multiplication of the clock is achieved by using an embedded PLL.

Data is converted from parallel to serial format and transmitted on the TXP and TXN differential outputs. The electrical connection of TXP and TXN can be interchanged through configuration. This option can be controlled by an input (TXPOLARITY) at the FPGA transmitter interface.

Deserializer

The serial transceiver input is locked to the input data stream through Clock and Data Recovery (CDR), a built-in feature of the RocketIO transceiver. CDR keys off the rising and falling edges of incoming data and derives a clock that is representative of the incoming data rate.

The derived clock, RXRECCLK, is generated and locked to as long as it remains within the specified component range. This clock is presented to the FPGA fabric at $^1/_{20}$ the incoming data rate.

A sufficient number of transitions must be present in the data stream for CDR to work properly. CDR requires approximately 5,000 transitions upon power-up to guarantee locking to the incoming data rate. Once lock is achieved, up to 75 missing transitions can be tolerated before lock to the incoming data stream is lost. The CDR circuit is guaranteed to work with 8B/10B encoding.

Another feature of CDR is its ability to accept an external precision reference clock, REFCLK, which either acts to clock incoming data or to assist in synchronizing the derived RXRECCLK.

For further clarity, the TXUSRCLK is used to clock data from the FPGA fabric to the TX FIFO. The FIFO depth accounts for the slight phase difference between these two clocks. If the clocks are locked in frequency, then the FIFO acts much like a pass-through buffer.

The receiver can be configured to reverse the RXP and RXN inputs. This can be useful in the event that printed circuit board traces have been reversed.

Receiver Termination

On-chip termination is provided at the receiver, eliminating the need for external termination. The receiver includes programmable on-chip termination circuitry for 50Ω (default) or 75Ω impedance, as shown in Figure 11.

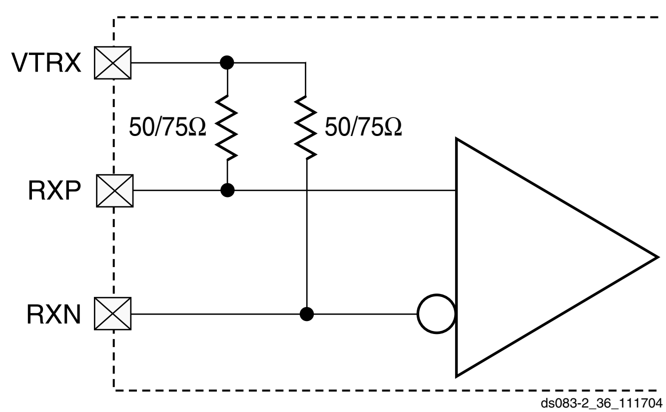

Figure 11: **RocketIO Receive Termination**

PCS

Fabric Data Interface

Internally, the PCS operates in 2-byte mode (16/20 bits). The FPGA fabric interface can either be 1, 2, or 4 bytes wide. When accompanied by the predefined modes of the PMA, the user thus has a large combination of protocols and data rates from which to choose.

USRCLK2 clocks data on the fabric side, while USRCLK clocks data on the PCS side. This creates distinct USRCLK/USRCLK2 frequency ratios for different combinations of fabric and internal data widths. Table 5 summarizes the USRCLK2 to USRCLK ratios for the three fabric data widths.

No fixed phase relationship is assumed between REFCLK, RXRECCLK, and/or any other clock that is not tied to either of these clocks. When RXUSRCLK and RXUSRCLK2 have different frequencies, each edge of the slower clock is aligned to a falling edge of the faster clock. The same relationships apply to TXUSRCLK and TXUSRCLK2.

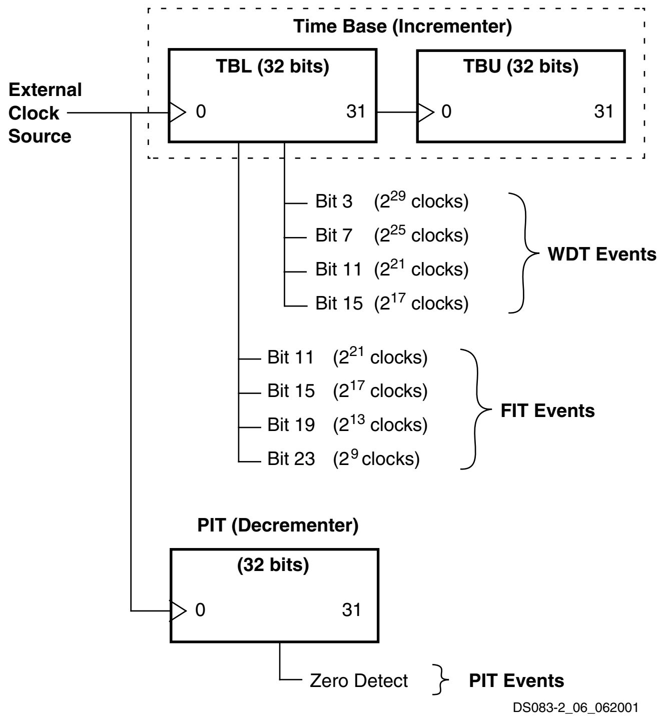

Figure 17: **Relationship of Timer Facilities to Base Clock**

Interrupts

The PPC405 provides an interface to an interrupt controller that is logically outside the PPC405 core. This controller combines the asynchronous interrupt inputs and presents them to the embedded core as a single interrupt signal. The sources of asynchronous interrupts are external signals, the JTAG/debug unit, and any implemented peripherals.

Debug Logic

All architected resources on the embedded PPC405 core can be accessed through the debug logic. Upon a debug event, the PPC405 core provides debug information to an external debug tool. Three different types of tools are supported depending on the debug mode: ROM monitors, JTAG debuggers, and instruction trace tools.

In internal debug mode, a debug event enables exception-handling software at a dedicated interrupt vector to take over the CPU core and communicate with a debug tool. The debug tool has read-write access to all registers and can set hardware or software breakpoints. ROM monitors typically use the internal debug mode.

In external debug mode, the CPU core enters stop state (stops instruction execution) when a debug event occurs. This mode offers a debug tool read-write access to all registers in the PPC405 core. Once the CPU core is in stop state, the debug tool can start the CPU core, step an instruction, freeze the timers, or set hardware or software break points. In addition to CPU core control, the debug logic is capable of writing instructions into the instruction cache, eliminating the need for external memory during initial board bring-up. Communication to a debug tool using external debug mode is through the JTAG port.

Debug wait mode offers the same functionality as external debug mode with one exception. In debug wait mode, the CPU core goes into wait state instead of stop state after a debug event. Wait state is identical to stop state until an interrupt occurs. In wait state, the PPC405 core can vector to an exception handler, service an interrupt and return to wait state. This mode is particularly useful when debugging real time control systems.

Real-time trace debug mode is always enabled. The debug logic continuously broadcasts instruction trace information to the trace port. When a debug event occurs, the debug logic signals an external debug tool to save instruction trace information before and after the event. The number of instructions traced depends on the trace tool.

Debug events signal the debug logic to stop the CPU core, put the CPU core in debug wait state, cause a debug exception or save instruction trace information.

Big Endian and Little Endian Support

The embedded PPC405 core supports big endian or little endian byte ordering for instructions stored in external memory. Since the PowerPC architecture is big endian internally, the ICU rearranges the instructions stored as little endian into the big endian format. Therefore, the instruction cache always contains instructions in big endian format so that the byte ordering is correct for the execution unit. This feature allows the 405 core to be used in systems designed to function in a little endian environment.

Table 9: **Supported Differential Signal I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Output V_{OD}
LDT_25	2.5	N/R	N/R	0.500 – 0.740
LVDS_25	2.5	N/R	N/R	0.247 – 0.454
LVDSEXT_25	2.5	N/R	N/R	0.440 – 0.820
BLVDS_25	2.5	N/R	N/R	0.250 – 0.450
ULVDS_25	2.5	N/R	N/R	0.500 – 0.740
LVPECL_25	2.5	N/R	N/R	0.345 – 1.185
LDT_25_DT(1)	2.5	2.5	N/R	0.500 – 0.740
LVDS_25_DT(1)	2.5	2.5	N/R	0.247 – 0.454
LVDSEXT_25_DT(1)	2.5	2.5	N/R	0.330 – 0.700
ULVDS_25_DT(1)	2.5	2.5	N/R	0.500 – 0.740

Notes:
1. These standards support on-chip 100Ω termination.
2. N/R = no requirement.

Table 10: **Supported DCI I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Termination Type
LVDCI_33(1)	3.3	3.3	N/R	Series
LVDCI_25	2.5	2.5	N/R	Series
LVDCI_DV2_25	2.5	2.5	N/R	Series
LVDCI_18	1.8	1.8	N/R	Series
LVDCI_DV2_18	1.8	1.8	N/R	Series
LVDCI_15	1.5	1.5	N/R	Series
LVDCI_DV2_15	1.5	1.5	N/R	Series
GTL_DCI	1.2	1.2	0.8	Single
GTLP_DCI	1.5	1.5	1.0	Single
HSTL_I_DCI	1.5	1.5	0.75	Split
HSTL_II_DCI	1.5	1.5	0.75	Split
HSTL_III_DCI	1.5	1.5	0.9	Single
HSTL_IV_DCI	1.5	1.5	0.9	Single
HSTL_I_DCI_18	1.8	1.8	0.9	Split
HSTL_II_DCI_18	1.8	1.8	0.9	Split
HSTL_III_DCI_18	1.8	1.8	1.1	Single
HSTL_IV_DCI_18	1.8	1.8	1.1	Single
SSTL2_I_DCI(2)	2.5	2.5	1.25	Split
SSTL2_II_DCI(2)	2.5	2.5	1.25	Split
SSTL18_I_DCI (3)	1.8	1.8	0.9	Split
SSTL18_II_DCI	1.8	1.8	0.9	Split

Table 10: **Supported DCI I/O Standards *(Continued)***

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Termination Type
LVDS_25_DCI	2.5	2.5	N/R	Split
LVDSEXT_25_DCI	2.5	2.5	N/R	Split

Notes:
1. LVDCI_XX is LVCMOS output controlled impedance buffers, matching all or half of the reference resistors.
2. These are SSTL compatible.
3. SSTL18_I is not a JEDEC-supported standard.
4. N/R = no requirement.

Logic Resources

IOB blocks include six storage elements, as shown in Figure 19.

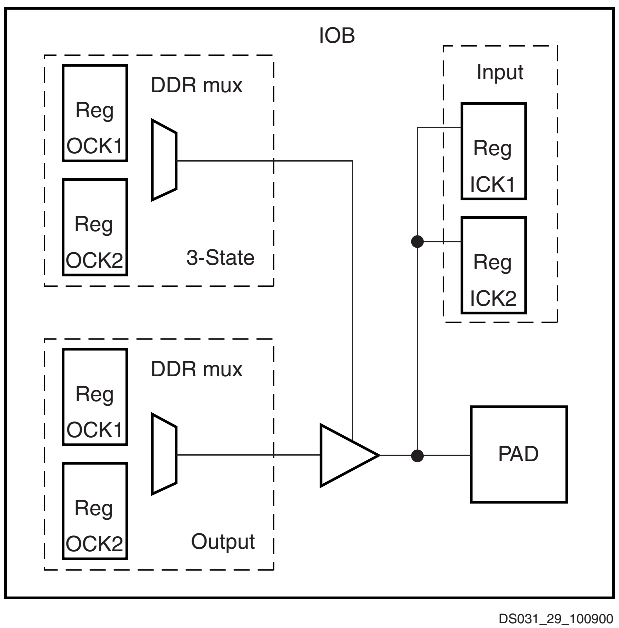

Figure 19: **Virtex-II Pro IOB Block**

Each storage element can be configured either as an edge-triggered D-type flip-flop or as a level-sensitive latch. On the input, output, and 3-state path, one or two DDR registers can be used.

Double data rate is directly accomplished by the two registers on each path, clocked by the rising edges (or falling edges) from two different clock nets. The two clock signals are generated by the DCM and must be 180 degrees out of phase, as shown in Figure 20. There are two input, output, and 3-state data signals, each being alternately clocked out.

Figure 36, Figure 37, and Figure 38 illustrate various example configurations.

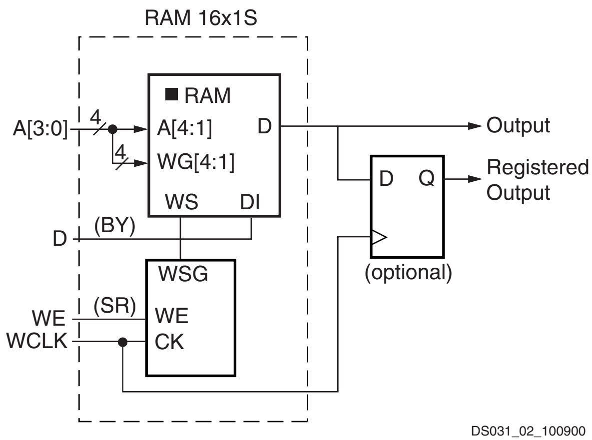

Figure 36: **Distributed SelectRAM+ (RAM16x1S)**

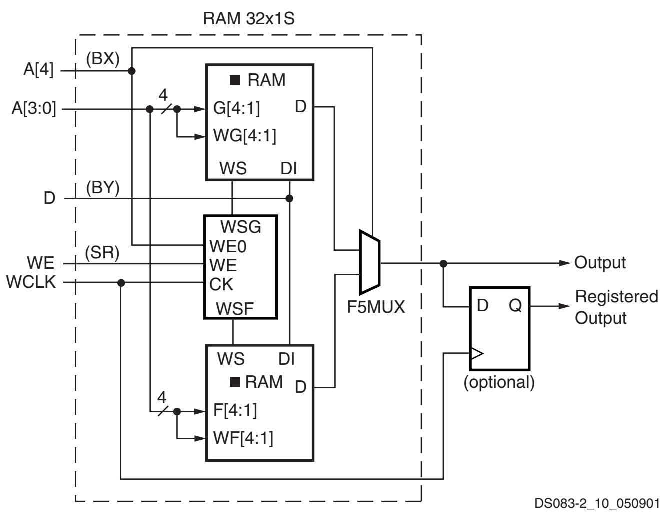

Figure 37: **Single-Port Distributed SelectRAM+ (RAM32x1S)**

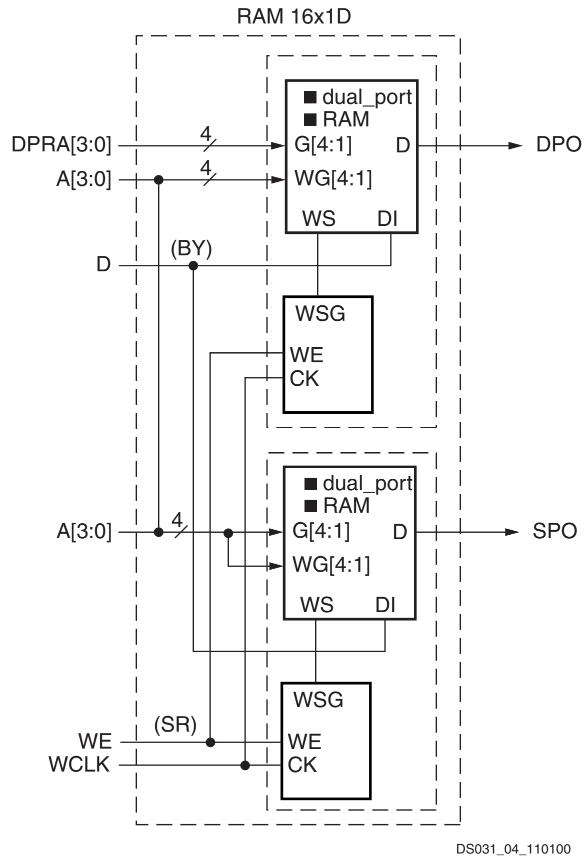

Figure 38: **Dual-Port Distributed SelectRAM+ (RAM16x1D)**

Similar to the RAM configuration, each function generator (LUT) can implement a 16 x 1-bit ROM. Five configurations are available: ROM16x1, ROM32x1, ROM64x1, ROM128x1, and ROM256x1. The ROM elements are cascadable to implement wider or/and deeper ROM. ROM contents are loaded at configuration. Table 17 shows the number of LUTs occupied by each configuration.

Table 17: **ROM Configuration**

ROM	Number of LUTs
16 x 1	1
32 x 1	2
64 x 1	4
128 x 1	8 (1 CLB)
256 x 1	16 (2 CLBs)

- The double lines route signals to every first or second block away in all four directions. Organized in a staggered pattern, double lines can be driven only at their endpoints. Double-line signals can be accessed either at the endpoints or at the midpoint (one block from the source).
- The direct connect lines route signals to neighboring blocks: vertically, horizontally, and diagonally.
- The fast connect lines are the internal CLB local interconnections from LUT outputs to LUT inputs.

Dedicated Routing

In addition to the global and local routing resources, dedicated signals are available.

- There are eight global clock nets per quadrant. (See Global Clock Multiplexer Buffers, page 48.)
- Horizontal routing resources are provided for on-chip 3-state buses. Four partitionable bus lines are provided per CLB row, permitting multiple buses within a row. (See 3-State Buffers, page 43.)
- Two dedicated carry-chain resources per slice column (two per CLB column) propagate carry-chain MUXCY output signals vertically to the adjacent slice. (See CLB/Slice Configurations, page 44.)
- One dedicated SOP chain per slice row (two per CLB row) propagate ORCY output logic signals horizontally to the adjacent slice. (See Sum of Products, page 42.)
- One dedicated shift-chain per CLB connects the output of LUTs in shift-register mode to the input of the next LUT in shift-register mode (vertically) inside the CLB. (See Shift Registers, page 39.)

Table 3: **DC Characteristics Over Recommended Operating Conditions**

Symbol	Description	Virtex-II Pro X			Virtex-II Pro			Units
		Min	Typ	Max	Min	Typ	Max	
V_{DRINT}	Data retention V_{CCINT} voltage (below which configuration data might be lost)	1.25			1.25			V
V_{DRI}	Data retention V_{CCAUX} voltage (below which configuration data might be lost)	2.0			2.0			V
I_{REF}	V_{REF} current per pin			10			10	µA
I_L	Input or output leakage current per pin (sample-tested)			10			10	µA
C_{IN}	Input capacitance (sample-tested)			10			10	pF
I_{RPU}	Pad pull-up (when selected) @ V_{in} = 0V, V_{CCO} = 2.5V (sample tested)			150			150	µA
I_{RPD}	Pad pull-down (when selected) @ V_{in} = 2.5V (sample-tested)			150			150	µA
I_{BATT}(1)	Battery supply current	Note (2)			Note (2)			nA
$I_{CCAUXTX}$	Operating AVCCAUXTX supply current		115			60	105	mA
$I_{CCAUXRX}$	Operating AVCCAUXRX supply current		85			35	75	mA
I_{TTX}	Operating I_{TTX} supply current when transmitter is AC-coupled		55			30		mA
	Operating I_{TTX} supply current when transmitter is DC-coupled	N/A	N/A	N/A		15		mA
I_{TRX}	Operating I_{TRX} supply current when receiver is AC-coupled		15			0		mA
	Operating I_{TRX} supply current when receiver is DC-coupled	N/A	N/A	N/A		15		
P_{CPU}	Power dissipation of PowerPC™ 405 processor block		0.9			0.9		mW/MHz
P_{RXTX}(3)	Power dissipation of MGT @ 1.25 Gb/s per channel	N/A	N/A	N/A		230		mW
	Power dissipation of MGT @ 2.5 Gb/s per channel		290			310		mW
	Power dissipation of MGT @ 3.125 Gb/s per channel		310			350		mW
	Power dissipation of MGT @ 4.25 Gb/s per channel		450		N/A	N/A	N/A	mW
	Power dissipation of MGT @ 6.25 Gb/s per channel		525		N/A	N/A	N/A	mW

Notes:
1. Characterized, not tested.
2. Battery supply current (I_{BATT}):

	Device Unpowered	Device Powered	Units
25°C:	< 50	< 10	nA
85°C:	N/A	< 10	nA

3. Total dissipation of fully operational PMA and PCS combined. This power is the average power supply dissipation per MGT. The averaging was done by simultaneously turning on all eight transceivers and dividing the total power supply dissipation by eight.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device initialization. The actual current consumed depends on the power-on ramp rate of the power supply.

The V_{CCINT} power supply must ramp on, monotonically, no faster than 200 μs and no slower than 50 ms. Ramp-on is defined as: 0 V_{DC} to minimum supply voltages (see Table 2).

V_{CCAUX} and V_{CCO} can power on at any ramp rate. Power supplies can be turned on in any sequence.

Table 5 shows the minimum current required by Virtex-II Pro devices for proper power-on and configuration.

If the current minimums shown in Table 5 are met, the device powers on properly after all three supplies have passed through their power-on reset threshold voltages.

Once initialized and configured, use the power calculator to estimate current drain on these supplies.

For more information on V_{CCAUX}, V_{CCO}, and configuration mode, refer to Chapter 3 in the *Virtex-II Pro Platform FPGA User Guide*.

Table 5: **Power-On Current for Virtex-II Pro Devices**

Symbol	Device											Units
	XC2VP2	XC2VP4	XC2VP7	XC2VP20	XC2VPX20	XC2VP30	XC2VP40	XC2VP50	XC2VP70	XC2VPX70	XC2VP100	
$I_{CCINTMIN}$	500	500	500	600	600	800	1050	1250	1700	1700	2200	mA
$I_{CCAUXMIN}$	250	250	250	250	250	250	250	250	250	250	250	mA
I_{CCOMIN}	100	100	100	100	100	100	100	100	100	100	100	mA

Notes:
1. Power-on current parameter values are specified for Commercial Grade. For Industrial Grade values, multiply Commercial Grade values by 1.5.
2. I_{CCOMIN} values listed here apply to the entire device (all banks).

General Power Supply Requirements

Proper decoupling of all FPGA power supplies is essential. Consult Xilinx Application Note **XAPP623** for detailed information on power distribution system design.

V_{CCAUX} powers critical resources in the FPGA. Therefore, this supply voltage is especially susceptible to power supply noise. V_{CCAUX} can share a power plane with V_{CCO}, but only if V_{CCO} does not have excessive noise. Staying within simultaneously switching output (SSO) limits is essential for keeping power supply noise to a minimum. Refer to **XAPP689**, "Managing Ground Bounce in Large FPGAs," to determine the number of simultaneously switching outputs allowed per bank at the package level.

Changes in V_{CCAUX} voltage beyond 200 mV peak-to-peak should take place at a rate no faster than 10 mV per millisecond.

Recommended practices that can help reduce jitter and period distortion are described in Xilinx Answer Record 13756.

Table 24: **RocketIO X Receiver Switching Characteristics**[1]

Description	Symbol	Conditions	Min	Typ	Max	Units
Receive total jitter tolerance using default equalization and PRBS-15 pattern	T_{JTOL}	2.488 Gb/s		0.80	0.65	UI[2]
		3.125 Gb/s		0.80	0.65	UI
		4.25 Gb/s		0.80	0.65	UI
		6.25 Gb/s		0.80	0.65	UI
Receive random jitter tolerance	T_{RJTOL}	2.488 Gb/s		0.30		UI
		3.125 Gb/s		0.30		UI
		4.25 Gb/s		0.30		UI
		6.25 Gb/s		0.30		UI
Receive sinusoidal jitter tolerance measured at 70 MHz	T_{SJTOL}	2.488 Gb/s		0.30	0.15	UI
		3.125 Gb/s		0.30	0.15	UI
		4.25 Gb/s		0.30	0.15	UI
		6.25 Gb/s		0.30	0.15	UI
Receive deterministic jitter tolerance	T_{DJTOL}	2.488 Gb/s		0.55	0.45	UI
		3.125 Gb/s		0.55	0.45	UI
		4.25 Gb/s		0.55	0.45	UI
		6.25 Gb/s		0.50	0.45	UI
Receive latency[3]	T_{RXLAT}			25	34[4]	RXUSRCLK cycles
RXUSRCLK duty cycle	T_{RXDC}		45	50	55	%
RXUSRCLK2 duty cycle	T_{RX2DC}		45	50	55	%
Differential receive input sensitivity	V_{EYE}			120	250	mV

Notes:
1. The XC2VPX70 operates at a fixed 4.25 Gb/s baud rate.
2. UI = Unit Interval
3. Receive latency delay RXP/RXN to RXDATA. Refer to ***RocketIO X Transceiver User Guide*** for more information on calculating latency.
4. This maximum may occur when certain conditions are present and clock correction and channel bonding are enabled. If these functions are both disabled, the maximum will be near the typical values.

Table 26: **RocketIO X Transmitter Switching Characteristics**[1]

Description	Symbol	Conditions	BREFCLK Frequency	Min	Typ	Max	Units
Serial data rate	F_{GTX}			2.488		6.25	Gb/s
Serial data output total jitter (p-p)[3]	T_{TJ}	2.488 Gb/s			0.15	0.20	UI[2]
		3.125 Gb/s			0.14	0.19	UI
		4.25 Gb/s			0.39	0.48	UI
		6.25 Gb/s			0.42	0.54	UI
Serial data output deterministic jitter (p-p)[3]	T_{DJ}	2.488 Gb/s	155.52 MHz		0.03	0.17	UI
		3.125 Gb/s	156.25 MHz		0.03	0.17	UI
		4.25 Gb/s	212.5 MHz		0.14	0.26	UI
		6.25 Gb/s	312.5 MHz		0.17	0.35	UI
Serial data output random jitter (p-p)[3,4]	T_{RJ}	2.488 Gb/s	155.52 MHz		0.12	0.18	UI
		3.125 Gb/s	156.25 MHz		0.12	0.20	UI
		4.25 Gb/s	212.5 MHz		0.25	0.39	UI
		6.25 Gb/s	312.5 MHz		0.25	0.39	UI
TX rise time	T_{RTX}	20% – 80% @ 2.500 Gb/s			60		ps
TX fall time	T_{FTX}				60		ps
Transmit latency[5]	T_{TXLAT}				14	19	TXUSR CLK cycles
TXUSRCLK duty cycle	T_{TXDC}			45	50	55	%
TXUSRCLK2 duty cycle	T_{TX2DC}			45	50	55	%

Notes:
1. The XC2VPX70 operates at a fixed 4.25 Gb/s baud rate.
2. UI = Unit Interval
3. Total Jitter $T_{TJ} = T_{DJ} + T_{RJ}$
4. T_{RJ} specifications are *wideband* and include low-frequency jitter components (also referred to as *wander*). T_{RJ} specified is peak-to-peak, estimated at BER=10^{-12} using the Bathtub Method.
5. Transmit latency delay TXDATA to TXP/TXN. Refer to ***RocketIO X Transceiver User Guide*** for more information on calculating latency.

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
0	IO_L53_0/No_Pair		A21	NC		
0	IO_L54N_0		H18	NC		
0	IO_L54P_0		G18	NC		
0	IO_L56N_0		C21	NC		
0	IO_L56P_0		C20	NC		
0	IO_L57N_0		J17	NC		
0	IO_L57P_0/VREF_0		H17	NC		
0	IO_L67N_0		E17			
0	IO_L67P_0		D17			
0	IO_L68N_0		D18			
0	IO_L68P_0		C18			
0	IO_L69N_0		J16			
0	IO_L69P_0/VREF_0		H16			
0	IO_L73N_0		E16			
0	IO_L73P_0		D16			
0	IO_L74N_0/GCLK7P		C16			
0	IO_L74P_0/GCLK6S		B16			
0	IO_L75N_0/GCLK5P	BREFCLKN	G16			
0	IO_L75P_0/GCLK4S	BREFCLKP	F16			
1	IO_L75N_1/GCLK3P		F15			
1	IO_L75P_1/GCLK2S		G15			
1	IO_L74N_1/GCLK1P		B15			
1	IO_L74P_1/GCLK0S		C15			
1	IO_L73N_1		D15			
1	IO_L73P_1		E15			
1	IO_L69N_1/VREF_1		H15			
1	IO_L69P_1		J15			
1	IO_L68N_1		C13			
1	IO_L68P_1		D13			
1	IO_L67N_1		D14			
1	IO_L67P_1		E14			
1	IO_L57N_1/VREF_1		H14	NC		
1	IO_L57P_1		J14	NC		
1	IO_L56N_1		C11	NC		
1	IO_L56P_1		C10	NC		

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
2	IO_L38N_2	N10				
2	IO_L38P_2	N9				
2	IO_L39N_2	M7				
2	IO_L39P_2	M6				
2	IO_L40N_2/VREF_2	L2				
2	IO_L40P_2	M2				
2	IO_L41N_2	N8				
2	IO_L41P_2	N7				
2	IO_L42N_2	L4				
2	IO_L42P_2	L3				
2	IO_L43N_2	M4				
2	IO_L43P_2	M3				
2	IO_L44N_2	P10				
2	IO_L44P_2	P9				
2	IO_L45N_2	N6				
2	IO_L45P_2	N5				
2	IO_L46N_2/VREF_2	M1				
2	IO_L46P_2	N1				
2	IO_L47N_2	P8				
2	IO_L47P_2	P7				
2	IO_L48N_2	N4				
2	IO_L48P_2	N3				
2	IO_L49N_2	N2				
2	IO_L49P_2	P2				
2	IO_L50N_2	R10				
2	IO_L50P_2	R9				
2	IO_L51N_2	P6				
2	IO_L51P_2	P5				
2	IO_L52N_2/VREF_2	P4				
2	IO_L52P_2	P3				
2	IO_L53N_2	T11				
2	IO_L53P_2	U11				
2	IO_L54N_2	R7				
2	IO_L54P_2	R6				
2	IO_L55N_2	P1				
2	IO_L55P_2	R1				
2	IO_L56N_2	T10				
2	IO_L56P_2	T9				

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
7	IO_L51P_7	N31		
7	IO_L51N_7	P31		
7	IO_L50P_7	T27		
7	IO_L50N_7	R28		
7	IO_L49P_7	M33		
7	IO_L49N_7	M34		
7	IO_L48P_7	M31		
7	IO_L48N_7	M32		
7	IO_L47P_7	R24		
7	IO_L47N_7	R25		
7	IO_L46P_7	M29		
7	IO_L46N_7/VREF_7	M30		
7	IO_L45P_7	L33		
7	IO_L45N_7	L34		
7	IO_L44P_7	P27		
7	IO_L44N_7	P28		
7	IO_L43P_7	L29		
7	IO_L43N_7	L30		
7	IO_L42P_7	K33		
7	IO_L42N_7	K34		
7	IO_L41P_7	P26		
7	IO_L41N_7	R26		
7	IO_L40P_7	K32		
7	IO_L40N_7/VREF_7	L32		
7	IO_L39P_7	K29		
7	IO_L39N_7	K30		
7	IO_L38P_7	P24		
7	IO_L38N_7	P25		
7	IO_L37P_7	J32		
7	IO_L37N_7	J33		
7	IO_L36P_7	J31		
7	IO_L36N_7	K31		
7	IO_L35P_7	N28		
7	IO_L35N_7	N29		
7	IO_L34P_7	H32		
7	IO_L34N_7/VREF_7	H33		
7	IO_L33P_7	H29		
7	IO_L33N_7	H30		

FF1517 Flip-Chip Fine-Pitch BGA Package

As shown in Table 12, XC2VP50 and XC2VP70 Virtex-II Pro devices are available in the FF1517 flip-chip fine-pitch BGA package. Following this table are the FF1517 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch).

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L01N_0/VRP_0	D31		
0	IO_L01P_0/VRN_0	E31		
0	IO_L02N_0	K30		
0	IO_L02P_0	J30		
0	IO_L03N_0	G30		
0	IO_L03P_0/VREF_0	H30		
0	IO_L05_0/No_Pair	K28		
0	IO_L06N_0	E30		
0	IO_L06P_0	F30		
0	IO_L07N_0	C30		
0	IO_L07P_0	D30		
0	IO_L08N_0	J29		
0	IO_L08P_0	K29		
0	IO_L09N_0	G29		
0	IO_L09P_0/VREF_0	H29		
0	IO_L19N_0	E29		
0	IO_L19P_0	F29		
0	IO_L20N_0	L28		
0	IO_L20P_0	L27		
0	IO_L21N_0	C29		
0	IO_L21P_0	D29		
0	IO_L25N_0	H28		
0	IO_L25P_0	J28		
0	IO_L26N_0	M27		
0	IO_L26P_0	M26		
0	IO_L27N_0	D28		
0	IO_L27P_0/VREF_0	E28		
0	IO_L28N_0	H27	NC	
0	IO_L28P_0	J27	NC	
0	IO_L29N_0	J26	NC	
0	IO_L29P_0	K26	NC	
0	IO_L30N_0	F28	NC	
0	IO_L30P_0	G27	NC	
0	IO_L34N_0	D27	NC	

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	IO_L30N_2	N6		
2	IO_L30P_2	N7		
2	IO_L31N_2	M4		
2	IO_L31P_2	N5		
2	IO_L32N_2	R11		
2	IO_L32P_2	R12		
2	IO_L33N_2	N1		
2	IO_L33P_2	N2		
2	IO_L34N_2/VREF_2	P6		
2	IO_L34P_2	P7		
2	IO_L35N_2	R13		
2	IO_L35P_2	T13		
2	IO_L36N_2	P4		
2	IO_L36P_2	P5		
2	IO_L37N_2	P3		
2	IO_L37P_2	N3		
2	IO_L38N_2	T10		
2	IO_L38P_2	T11		
2	IO_L39N_2	P1		
2	IO_L39P_2	P2		
2	IO_L40N_2/VREF_2	R7		
2	IO_L40P_2	R8		
2	IO_L41N_2	T12		
2	IO_L41P_2	U12		
2	IO_L42N_2	R5		
2	IO_L42P_2	R6		
2	IO_L43N_2	R3		
2	IO_L43P_2	R4		
2	IO_L44N_2	U8		
2	IO_L44P_2	T8		
2	IO_L45N_2	R1		
2	IO_L45P_2	R2		
2	IO_L46N_2/VREF_2	T6		
2	IO_L46P_2	T7		
2	IO_L47N_2	U9		
2	IO_L47P_2	U10		
2	IO_L48N_2	T2		
2	IO_L48P_2	T3		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	AVCCAUXTX6	B23		
N/A	VTTXPAD6	B24		
N/A	TXNPAD6	A24		
N/A	TXPPAD6	A23		
N/A	GNDA6	C24		
N/A	RXPPAD6	A22		
N/A	RXNPAD6	A21		
N/A	VTRXPAD6	B22		
N/A	AVCCAUXRX6	B21		
N/A	AVCCAUXTX7	B18		
N/A	VTTXPAD7	B19		
N/A	TXNPAD7	A19		
N/A	TXPPAD7	A18		
N/A	GNDA7	C16		
N/A	RXPPAD7	A17		
N/A	RXNPAD7	A16		
N/A	VTRXPAD7	B17		
N/A	AVCCAUXRX7	B16		
N/A	AVCCAUXTX8	B14		
N/A	VTTXPAD8	B15		
N/A	TXNPAD8	A15		
N/A	TXPPAD8	A14		
N/A	GNDA8	C13		
N/A	RXPPAD8	A13		
N/A	RXNPAD8	A12		
N/A	VTRXPAD8	B13		
N/A	AVCCAUXRX8	B12		
N/A	AVCCAUXTX9	B10		
N/A	VTTXPAD9	B11		
N/A	TXNPAD9	A11		
N/A	TXPPAD9	A10		
N/A	GNDA9	C9		
N/A	RXPPAD9	A9		
N/A	RXNPAD9	A8		
N/A	VTRXPAD9	B9		
N/A	AVCCAUXRX9	B8		
N/A	AVCCAUXTX11	B6		
N/A	VTTXPAD11	B7		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
N/A	VCCINT	R17		
N/A	VCCINT	AE16		
N/A	VCCINT	AD16		
N/A	VCCINT	T16		
N/A	VCCINT	R16		
N/A	VCCINT	AE15		
N/A	VCCINT	AD15		
N/A	VCCINT	AC15		
N/A	VCCINT	AB15		
N/A	VCCINT	AA15		
N/A	VCCINT	Y15		
N/A	VCCINT	W15		
N/A	VCCINT	V15		
N/A	VCCINT	U15		
N/A	VCCINT	T15		
N/A	VCCINT	R15		
N/A	VCCINT	AF14		
N/A	VCCINT	P14		
N/A	VCCINT	AG13		
N/A	VCCINT	N13		
N/A	VCCINT	AH12		
N/A	VCCINT	M12		
N/A	VCCAUX	AV39		
N/A	VCCAUX	AA39		
N/A	VCCAUX	Y39		
N/A	VCCAUX	W39		
N/A	VCCAUX	B39		
N/A	VCCAUX	AW38		
N/A	VCCAUX	Y38		
N/A	VCCAUX	A38		
N/A	VCCAUX	AR35		
N/A	VCCAUX	E35		
N/A	VCCAUX	AP34		
N/A	VCCAUX	F34		
N/A	VCCAUX	AW20		
N/A	VCCAUX	AV20		
N/A	VCCAUX	B20		
N/A	VCCAUX	A20		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
2	IO_L02P_2		D7		
2	IO_L03N_2		E6		
2	IO_L03P_2		D6		
2	IO_L04N_2/VREF_2		G6		
2	IO_L04P_2		F7		
2	IO_L05N_2		D3		
2	IO_L05P_2		E3		
2	IO_L06N_2		D1		
2	IO_L06P_2		D2		
2	IO_L73N_2		E1		
2	IO_L73P_2		E2		
2	IO_L74N_2		F4		
2	IO_L74P_2		F3		
2	IO_L75N_2		F1		
2	IO_L75P_2		F2		
2	IO_L76N_2/VREF_2		G3		
2	IO_L76P_2		G4		
2	IO_L77N_2		G2		
2	IO_L77P_2		G1		
2	IO_L78N_2		G5		
2	IO_L78P_2		H6		
2	IO_L79N_2		H4		
2	IO_L79P_2		H5		
2	IO_L80N_2		H3		
2	IO_L80P_2		H2		
2	IO_L81N_2		H7		
2	IO_L81P_2		J8		
2	IO_L82N_2/VREF_2		J6		
2	IO_L82P_2		J7		
2	IO_L83N_2		J5		
2	IO_L83P_2		J4		
2	IO_L84N_2		J1		
2	IO_L84P_2		J2		
2	IO_L07N_2		K9		
2	IO_L07P_2		L10		
2	IO_L08N_2		K6		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	IO_L27P_7		P33		
7	IO_L27N_7		P34		
7	IO_L26P_7		N31		
7	IO_L26N_7		N32		
7	IO_L25P_7		N41		
7	IO_L25N_7		N42		
7	IO_L24P_7		N39		
7	IO_L24N_7		N40		
7	IO_L23P_7		N33		
7	IO_L23N_7		N34		
7	IO_L22P_7		N37		
7	IO_L22N_7/VREF_7		N38		
7	IO_L21P_7		N35		
7	IO_L21N_7		N36		
7	IO_L20P_7		M38		
7	IO_L20N_7		M39		
7	IO_L19P_7		M40		
7	IO_L19N_7		M41		
7	IO_L18P_7		M33		
7	IO_L18N_7		M34		
7	IO_L17P_7		M31		
7	IO_L17N_7		M32		
7	IO_L16P_7		M35		
7	IO_L16N_7/VREF_7		M36		
7	IO_L15P_7		L41		
7	IO_L15N_7		L42		
7	IO_L14P_7		L39		
7	IO_L14N_7		L38		
7	IO_L13P_7		L40		
7	IO_L13N_7		K40		
7	IO_L12P_7		L36		
7	IO_L12N_7		L37		
7	IO_L11P_7		L34		
7	IO_L11N_7		L35		
7	IO_L10P_7		K42		
7	IO_L10N_7/VREF_7		K41		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
1	IO_L21P_1	H13	
1	IO_L20N_1	L12	
1	IO_L20P_1	K12	
1	IO_L19N_1	B11	
1	IO_L19P_1	A11	
1	IO_L09N_1/VREF_1	E11	
1	IO_L09P_1	D11	
1	IO_L08N_1	J11	
1	IO_L08P_1	H11	
1	IO_L07N_1	G11	
1	IO_L07P_1	F11	
1	IO_L06N_1	B10	
1	IO_L06P_1	A10	
1	IO_L05_1/No_Pair	G10	
1	IO_L03N_1/VREF_1	C10	
1	IO_L03P_1	C11	
1	IO_L02N_1	L11	
1	IO_L02P_1	K11	
1	IO_L01N_1/VRP_1	F10	
1	IO_L01P_1/VRN_1	E10	
2	IO_L01N_2/VRP_2	B8	
2	IO_L01P_2/VRN_2	A8	
2	IO_L02N_2	C9	
2	IO_L02P_2	B9	
2	IO_L03N_2	B7	
2	IO_L03P_2	A7	
2	IO_L04N_2/VREF_2	B6	
2	IO_L04P_2	A6	
2	IO_L05N_2	D8	
2	IO_L05P_2	D9	
2	IO_L06N_2	B4	
2	IO_L06P_2	A4	
2	IO_L73N_2	C7	
2	IO_L73P_2	C8	
2	IO_L74N_2	G9	
2	IO_L74P_2	F9	